



* does not represent
actual color

SNN65-HXP Form-In-Place

A rapid-cure, Ag-coated Nickel-filled silicone elastomer Form-in-Place gasket material.

Laird Technologies introduces its newest line of FIP products, EMI-Sentry. These Form-In-Place pastes are extremely fast curing with reliable shielding effectiveness and strength.

Laird Technologies' Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. This product is particularly ideal for basestations, PDAs, PC cards, radios, mobile phones, as well as many other cast enclosures and packaged electronic assemblies.

TYPICAL VALUES

	TEST METHOD	UNITS	SNN65-HXP
Elastomer			Silicone
Filler			Ag/Ni
ELECTRICAL PROPERTIES			
Volume Resistivity		ohm-cm	0.005
Shielding Effectiveness	MIL-DTL-83528C		
200 MHz to 10 GHz	Para. 4.5.12	dB	>100
PHYSICAL PROPERTIES			
Hardness	ASTM D2240	Shore A	65
Density (cured)	ASTM D792	g/cm ³	3.84
Density (uncured)	LT-FIP-CLE-09	g/cm ³	3.78
Compression Set	ASTM D575	%	10*
Adhesion Strength (AI)	LT-FIP-CLE-03	N/cm ²	200
Compression-Deflection (a)	LT-FIP-CLE-07		
at 20% compression		lb/in	
at 40% compression		lb/in	
Temperature Range		°C	-50°C to 125°C
UL rating	UL-94		V0
CURING REQUIREMENTS			
Cure Conditions		120°C minimum	
Cure Time at 125°C (b)	LT-FIP-CLE-14		1.5 hours

(a) Compression-deflection bead size 0.60 mm (H) x 0.70 mm (W)

(b) Time to effectively cure a bead will necessarily depend on individual conditions, including bead size, shield size and weight, oven capacity, and oven ramp-rates.

rev. 05/27/10